112. In some embodiments, the thickness of the bracket 602 can be less than a length at which a component 116 extends from the circuit board 112 in order for the bracket 602 to resist bending of the circuit board 112. In some embodiments, the bracket 602 can extend closer to the components 116 in order to maximize surface area of the bracket 602 between the housing 108 and the circuit board 112, as illustrated in FIG. 6C. Specifically, FIG. 6C illustrates a perspective view of an embodiment of a bracket 608 that can be connected to the circuit board 112 in order to mitigate stress and tension on the components 116. The bracket 608 can include one or more inner walls that extend around a portion of one or more components 116. In this way, the outer perimeter of the bracket 608 can be reduced while increasing a surface area of bracket 608. It should be noted that any of the embodiments of the spacer and bracket discussed herein can be combined in any manner suitable for mitigating damage to computing device components caused by stress or tension. For example, in some embodiments, the bracket 602 can be incorporated on the circuit board 112 and the spacer 202 can be incorporated on the component 114 or on any other surface of the computing device 100.

[0031] FIG. 7 illustrates a method 700 for connecting a spacer to a computing device to protect components of the computing device from bending stresses. The method 700 can be performed by any computing device, apparatus, or manufacturing device suitable for connecting components. The method 700 can include a step 702 of forming a spacer for a component of a computing device to protect the component from bending stress. The spacer can be any of the spacers discussed with respect to FIGS. 1A-6C. Additionally, the computing device can be any device that includes components, including computing device 100 discussed herein. The method 700 can further include a step 704 of connecting the spacer to a surface of the component and/or a surface of the computing device. In this way, the spacer can mitigate bending stresses at the component.

[0032] FIG. 8 illustrates a method 800 for connecting a bracket to a surface of a computing device to protect components of the computing device from bending stress. The method 800 can be performed by any computing device, apparatus, or manufacturing device suitable for connecting components. The method 800 can include a step 802 of forming a bracket for a surface of a computing device to protect components of the computing device from bending stresses. The bracket can be any bracket discussed herein, such as the bracket 602 or bracket 608 of FIGS. 6A and 6B, and FIG. 6C respectively. The method 800 can further include a step 804 of connecting the bracket to the surface of the computing device or a component of the computing device. In this way, the bracket can mitigate bending stresses across the surface of the computing device.

[0033] The various aspects, embodiments, implementations or features of the described embodiments can be used separately or in any combination. Various aspects of the described embodiments can be implemented by software, hardware or a combination of hardware and software. The described embodiments can also be embodied as computer readable code on a computer readable medium for controlling manufacturing operations or as computer readable code on a computer readable medium for controlling a manufacturing line. The computer readable medium is any data storage device that can store data which can thereafter be read by a computer system. Examples of the computer readable medium include read-only memory, random-access memory, CD-ROMs, HDDs, DVDs, magnetic tape, and optical data storage devices. The computer readable medium can also be distributed over network-coupled computer systems so that the computer readable code is stored and executed in a distributed fashion.

[0034] The foregoing description, for purposes of explanation, used specific nomenclature to provide a thorough understanding of the described embodiments. However, it will be apparent to one skilled in the art that the specific details are not required in order to practice the described embodiments. Thus, the foregoing descriptions of specific embodiments are presented for purposes of illustration and description. They are not intended to be exhaustive or to limit the described embodiments to the precise forms disclosed. It will be apparent to one of ordinary skill in the art that many modifications and variations are possible in view of the above teachings.

What is claimed is:

1. A computing device, comprising:

a circuit board; and

a component connected to the circuit board, wherein the component includes a curved spacer disposed over a surface of the component for mitigating bending stresses at the component.

2. The computing device of claim **1**, further comprising:

a cover glass; and

a display assembly, wherein the surface of the component faces the display assembly and the cover glass.

3. The computing device of claim **1**, wherein a first thickness of the curved spacer is less than a second thickness of the component.

4. The computing device of claim **1**, wherein the curved spacer covers an entire area of the surface of the component.

5. The computing device of claim **1**, wherein the component is one of a central processing unit, a graphics processing unit, a power management unit, or a system on a chip.

6. The computing device of claim **1**, further comprising:

a bracket connected to the circuit board on a first side of the circuit board, wherein the component is connected to a second side of the circuit board.

7. The computing device of claim **6**, wherein the bracket surrounds one or more components of the circuit board on the first side of the circuit board.

8. A circuit component comprising:

processing circuitry;

a surface that at least partially covers the processing circuitry; and

a spacer disposed over the surface of the circuit component for preventing bending stresses from damaging the processing circuitry.

9. The circuit component of claim **8**, wherein the spacer includes a curved profile.

10. The circuit component of claim **9**, wherein the spacer spans a width of the surface of the circuit component.

11. The circuit component of claim **8**, wherein the spacer is made from injection molded metal, an injection molded plastic, or an epoxy.

12. The circuit component of claim **8**, wherein a thickness of the spacer is less than half of an entire thickness of the circuit component.

13. The circuit component of claim **8**, wherein the spacer is made from an epoxy that is infused with particles to increase thermal conductivity of the epoxy.